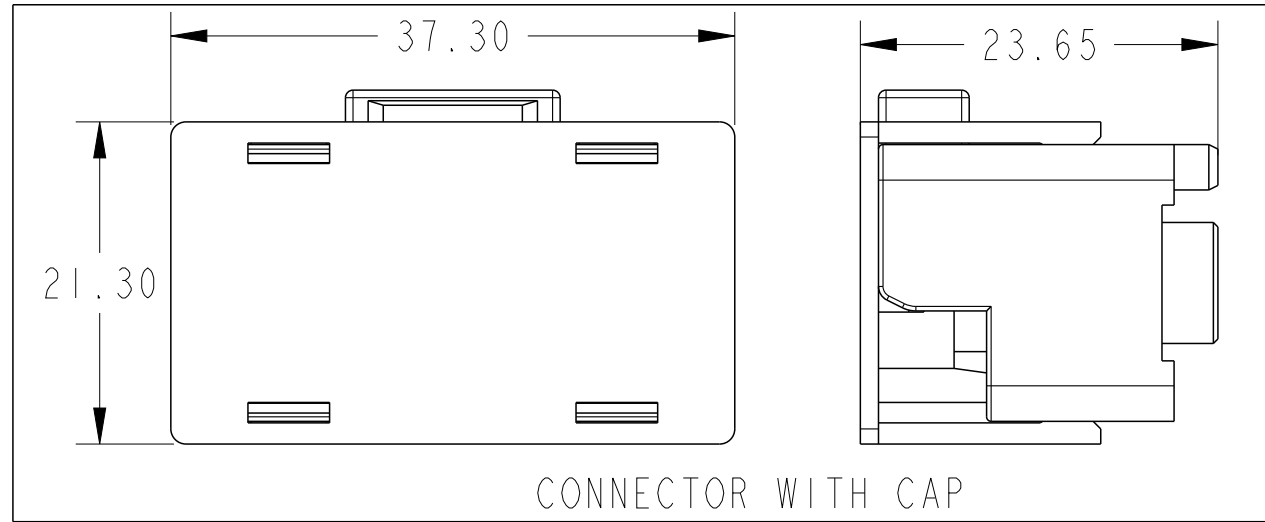
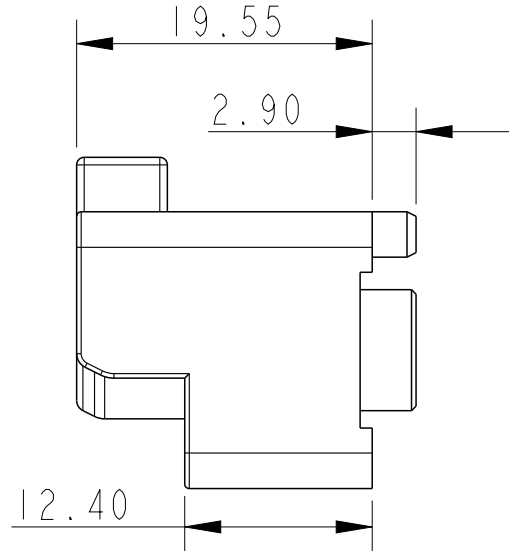
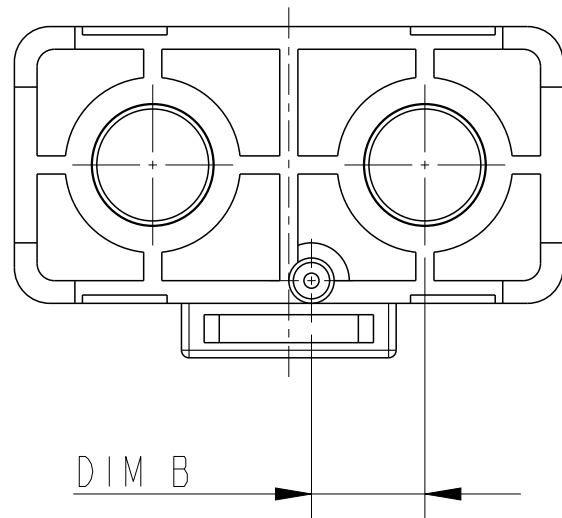
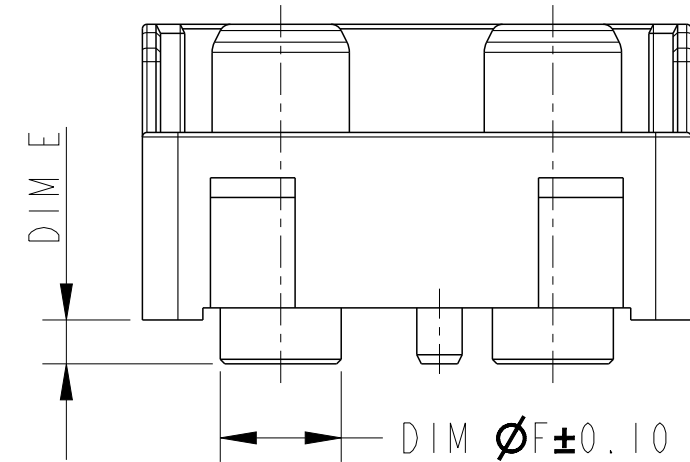
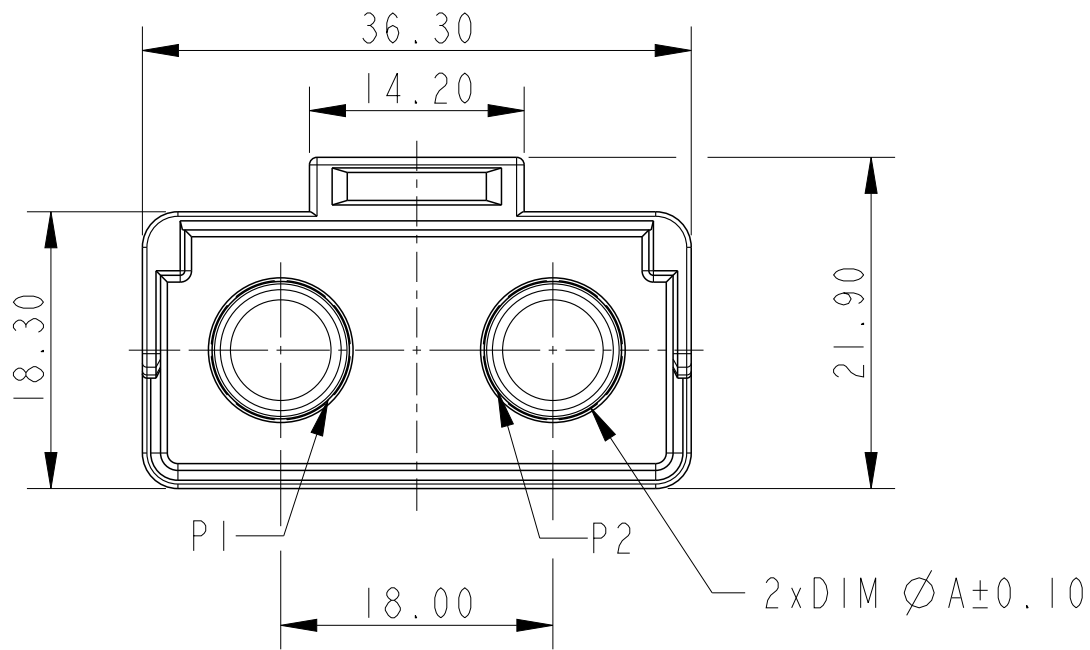


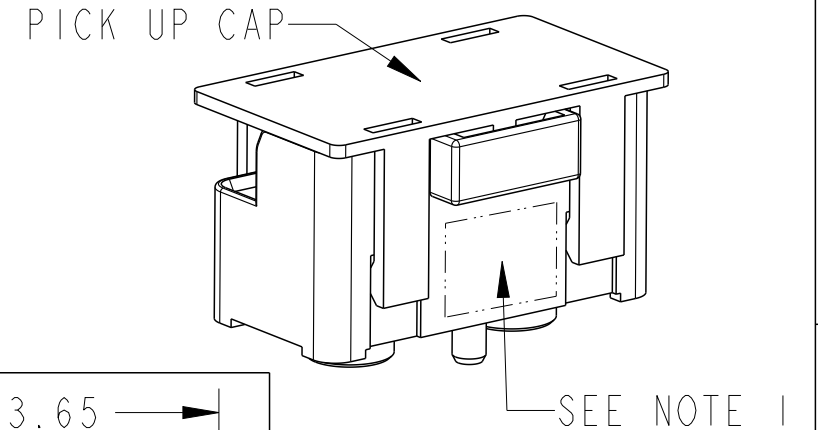
A

C

D



revision history				
rev	ecn no	description	dr	date
A	-	INITIAL RELEASE	LC	2026/03/04
-	-	-	-	YYYY/MM/DD
-	-	-	-	YYYY/MM/DD



A

B

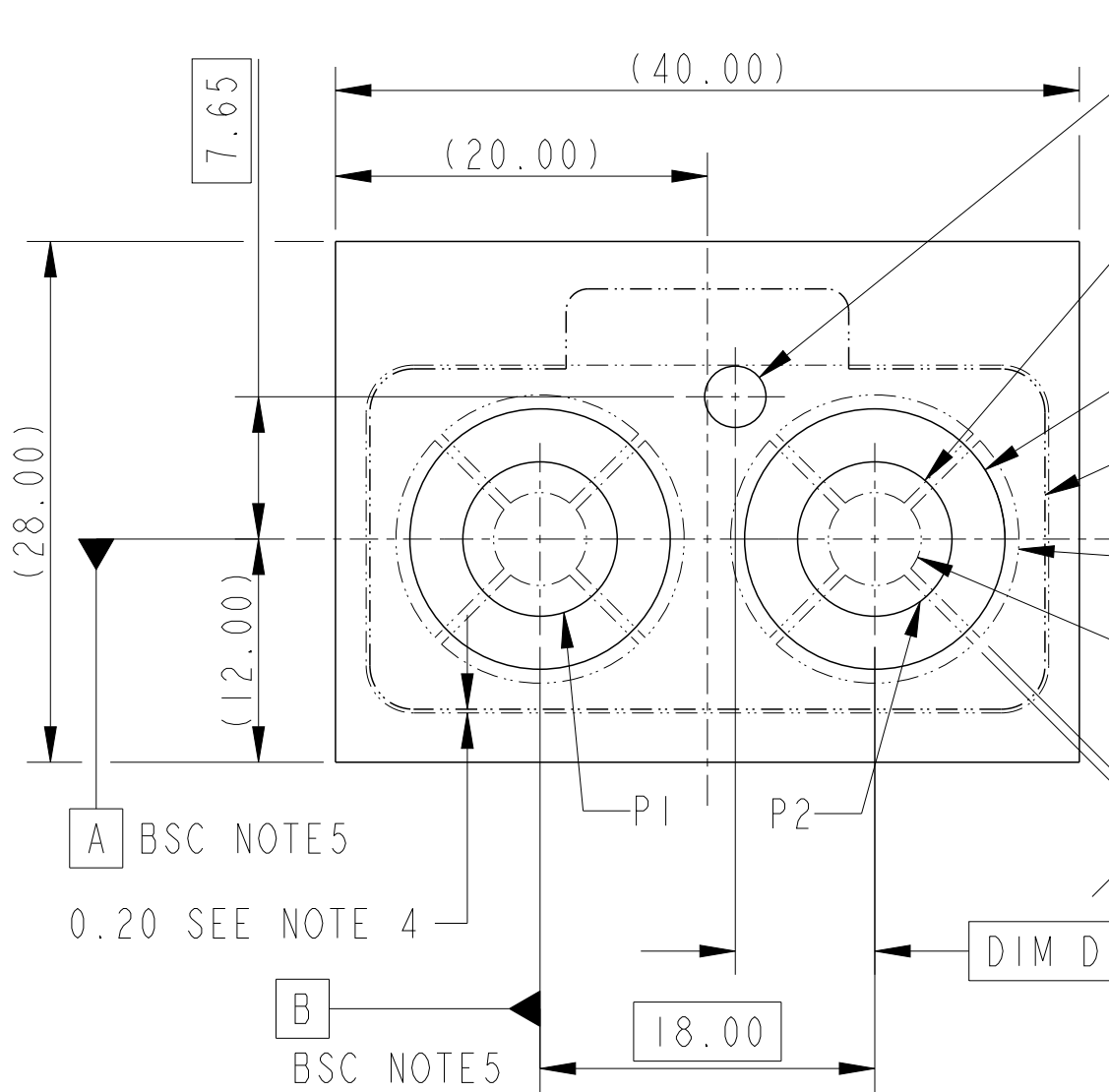
C

D

SERIES	PART NUMBER	PACKAGING	SOLDERING	PICK UP CAP	DIM A	DIM B	DIM E	DIM F (Ø)
9.1MM 250A/PIN	*10175071-001LF	SOFT TRAY	DIP(WAVE SOLDERING)	NO	9.10	7.50	4.40	7.90
	10175071-001CLF	JEDEC SOFT TRAY	PIP(REFLOW SOLDERING)	YES			2.90	8.00
	10175071-001PLF	HARD TRAY	PIP(REFLOW SOLDERING)	NO				
	10175071-001PCLF	HARD TRAY	PIP(REFLOW SOLDERING)	YES				
8.0MM 200A/PIN	*10175071-002LF	SOFT TRAY	DIP(WAVE SOLDERING)	NO	8.00	10.50	4.40	6.90
	*10175071-002CLF	JEDEC SOFT TRAY	PIP(REFLOW SOLDERING)	YES			2.90	7.00
	10175071-002PLF	HARD TRAY	PIP(REFLOW SOLDERING)	NO				
	10175071-002PCLF	HARD TRAY	PIP(REFLOW SOLDERING)	YES				

* =NOT TOOLED

spec ref				dr	Will Gao	2024/01/30	Amphenol Power Solutions				scale	size
tolerance std				eng	Dong, Qing-Fen	2026/03/09					2.000	A3
ISO 406 ISO 1101				rvwr	-	-					ecn no	ELX-DG-280526-1
TOLERANCES UNLESS OTHERWISE SPECIFIED				appr	Andy Lu	2026/03/10	A Division of Amphenol Corporation			amphenol-icc.com	rel lev	PDF Released
surface	linear	0.X	±0.5	projection		title	COOLPOWER HD 9.1MM & 8MM VT BOARD ASSEMBLY		dwg no	10175071		rev
		0.XX	±0.25									
		0.XXX	±0.13							cat. no.	-	
ISO 1302	angular	0°	±°	product family			-	Product - Customer Drw			sheet 1 of 2	

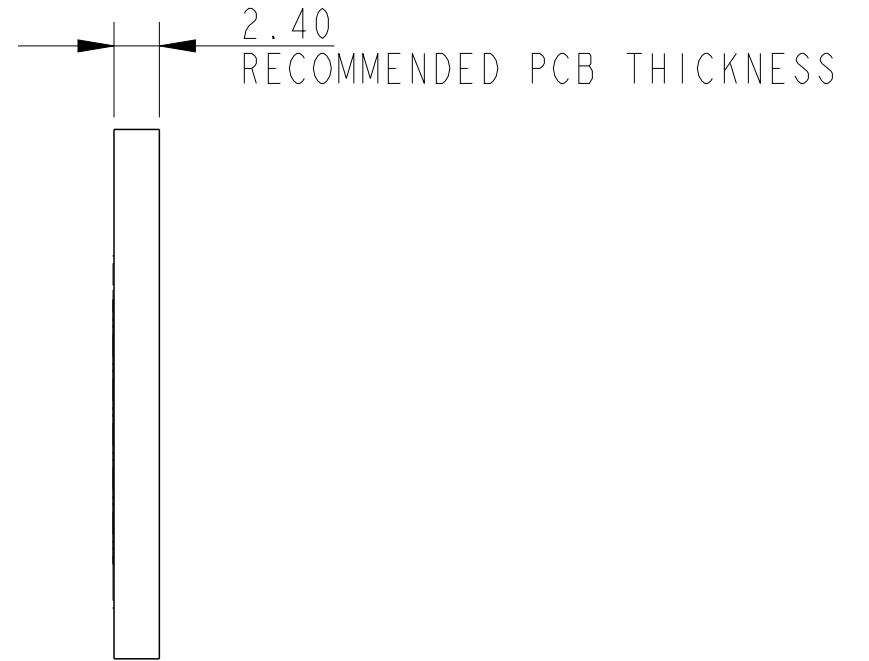


TOP VIEW
PCB LAYOUT
(RECOMMENDED STENCIL THICKNESS: 0.15MM)

- $\phi 3.30 \pm 0.05$ NPTH
 $\phi 0.08$ A B
DIM $\phi C \pm 0.05$ PTH
 $\phi 0.08$ A B
(2x $\phi 14.00$) PAD
SEE NOTE 10
STENCIL OPENING, PIP ONLY
 $\phi 15.50$
STENCIL OPENING, PIP ONLY
 $\phi 5.00$
STENCIL OPENING, PIP ONLY
0.50 TYP.

NOTE.

1. PRODUCT MARK PART NUMBER, MANUFACTURER'S NAME AND DATE CODE TO MARKED ON THIS SURFACE.
2. MATERIALS:
-HOUSING & PICK UP CAP: HIGH TEMP THERMOPLASTIC, UL94V-0, BLACK.
-POWER CONTACT: HIGH CONDUCTIVITY COPPER ALLOY.
3. PLATING SPECIFICATION:
TERMINALS: SILVER OVER NICKEL PLATING.
4. DENOTES CONNECTOR KEEP OUT ZONE.
5. DATUM AND BASIC DIMENSIONS ARE ESTABLISHED BY CUSTOMER.
6. ALL HOLE DIAMETERS ARE FINISHED HOLE SIZES.
7. THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS FOR PIP(REFLOW SOLDERING)AND DIP(WAVE SOLDERING).
8. THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-47-0004.
9. PRODUCT SPECIFICATION : GS-12-1941.
APPLICATION SPECIFICATION : GS-20-0908.
PRODUCT PACKAGE SPECIFICATION: GS-14-3141.
10. THE MODULE LINE OF THE MOUL.



SERIES	PCB APPLICATION	DIM C	DIM D
9.1MM 250A/PIN	10175071-001LF	8.30	7.50
	10175071-001CLF		
	10175071-001PLF		
	10175071-001PCLF		
8.0MM 200A/PIN	10175071-002LF	7.30	10.50
	10175071-002CLF		
	10175071-002PLF		
	10175071-002PCLF		

spec ref		dr		Will Gao		2024/01/30		Amphenol Power Solutions		← MM →		scale		size					
tolerance std		eng		Dong, Qing-Fen		2026/03/09						1.000		A3					
ISO 406 ISO 1101		r vwr		-		-				ec n no				ELX-DG-280526-1					
TOLERANCES UNLESS OTHERWISE SPECIFIED		appr		Andy Lu		2026/03/10		A Division of Amphenol Corporation		amphenol-icc.com		rel levPDF Released							
surface ISO 1302 ✓		linear		0.X ±0.5		0.XX ±0.25		0.XXX ±0.13		projection		title COOLPOWER HD 9.1MM & 8MM VT BOARD ASSEMBLY		dwg no		10175071		rev	
														cat. no.		-		A	
														product family		-		Product - Customer Drw	